

(Modified)

Patent and Trademark Office



Record the attached original documents

To the Honorable Commissioner or copy thereof

102573641

9-30-03

1. Name of conveying party(ies):

Robert Z. Bachrach . . . . . September 19, 2001
Jeffrey D. Chin . . . . . September 14, 2001

EXECUTION DATE

Additional name(s) of conveying part(ies) attached? [ ] Yes [X] No

2. Name and address of receiving party(ies):

Name: Applied Materials, Inc.

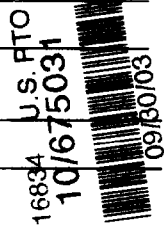
Internal Address: Patent Department

Street Address: P. O. Box 450A

M/S #2061

City: Santa Clara State CA Zip 95054

Additional Name(s) & address(es) attached? [ ] Yes [X] No



3. Nature of conveyance:

[X] Assignment [ ] Merger

[ ] Security Agreement [ ] Change of Name

Other

Execution Date: SEE ABOVE

4. Application number(s) or patent Number(s):

10675031

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

B. Patent No.(s)

Serial No.: 09/932,396 Filing Date: April 17, 2001

Additional Numbers attached? [ ] Yes [X] No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: PATENT COUNSEL

Internal Address: Applied Materials, Inc.

Patent Dept.

Street Address: P. O. Box 450A

M/S 2061

City: Santa Clara State: CA ZIP: 95052

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$40.00

[ ] Enclosed

[X] Authorized to be charged to deposit account

8. Deposit account number: 50-1074

(Attach duplicate copy of this page if paying by deposit account)

10/10/2003 ECDOPER 00000328 501074 10675031

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and any attached copy is a true copy of the original document.

Robert W. Mulcahy, Reg. No. 25,436
Name of Person Signing

Signature

Date

10/11/01

10. Total number of pages comprising cover sheet, attachments, and document: 5

OMB No. 0651-0011 (exp. 4/94)

**ASSIGNMENT FOR APPLICATION FOR PATENT**

WHEREAS:

Names and Addresses of Inventors:

1)	Robert Z. Bachrach 233 Chapin Lane Burlingame, California 94010-5209	2)	Jeffrey D. Chinn 605 St. Croix Lane Foster City, California 94404
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(hereinafter referred to as Assignors), have invented a certain invention entitled:

**METHOD AND APPARATUS FOR CHEMICAL-MECHANICAL-JET  
ETCHING OF SEMICONDUCTOR STRUCTURES**

for which an application for Letters Patent in the United States was filed on August 17, 2001, under U.S. Serial No. 09/932,396; and

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as the Application), and the invention disclosed therein (hereinafter referred to as the Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as the Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sell, assign, transfer and convey to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenant and agree to cooperate with said Assignee to

enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrant and represent that they have not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

IN WITNESS WHEREOF, the said Assignors have executed and delivered this instrument to said Assignee on the date indicated below.

1) \_\_\_\_\_, 2001

\_\_\_\_\_  
Robert Z. Bachrach

2) 9/19 \_\_\_\_\_, 2001

\_\_\_\_\_  
Jeffrey D. Chinn

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1) 9/19/01, 2001

Robert Z. Bachrach  
Robert Z. Bachrach

2) \_\_\_\_\_, 2001

\_\_\_\_\_  
Jeffrey D. Chinn